## **AMENDMENTS TO THE SPECIFICATION**

Docket No.: 09852/0205523-US0

Please change the title as follows:

SILICON ELECTRODE PLATE FOR PLASMA ETCHING WITH SUPERIOR DURABILITY

Please remove the sentence starting from line 9 under TECHNICAL FIELD on page 1 and add the paragraph as follows:

This application claims priority from Japanese Patent Application No. 2004-108731 filed on April-1, 2004 and Japanese patent Application No. 2004-234961 filed on August 12, 2004, the contents of which are incorporated herein by reference.

## Cross-Reference to Prior Application

This is a U.S. National Phase Application under 35 U.S.C. §371 of International Patent Application No. PCT/JP2005/006134 filed March 30, 2005, and claims the benefit of Japanese Patent Applications No. 2004-108731, filed April 1, 2004 and 2004-234961, filed August 12, 2004, all of which are incorporated by reference herein. The International Application was published in Japanese on October 13, 2005 as WO 2005/096361 A1 under PCT Article 21(2).

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